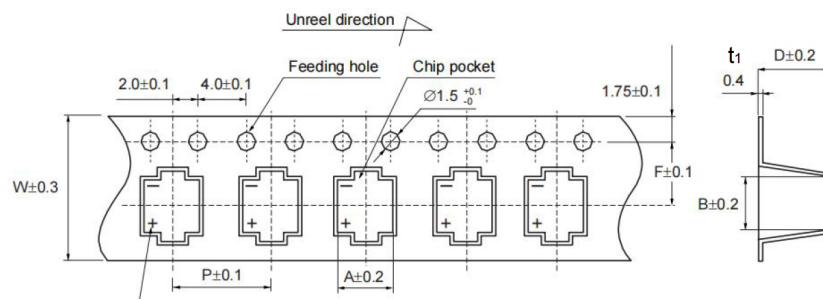


• SMD Type Taping Specifications

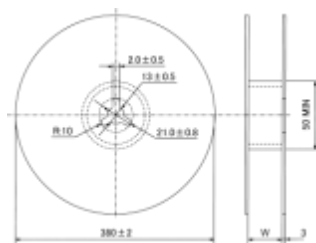
• Carrier Tape Dimensions



unit : mm

Case size	W	A	B	P	F	t ₁	D
	±0.3	±0.2	±0.2	±0.1	±0.1	±0.1	±0.2
6.3 x 6.0	16.0	7.0	7.0	12.0	7.5	0.4	6.4
6.3 x 7.7	16.0	7.0	7.0	12.0	7.5	0.4	8.4
8 x 10	24.0	8.7	8.7	16.0	11.5	0.4	11.0
8 x 12.5	24.0	8.7	8.7	16.0	11.5	0.4	13.2
10 x 10.5	24.0	10.7	10.7	16.0	11.5	0.4	11.0
10 x 12.8	24.0	10.7	10.7	16.0	11.5	0.4	13.2
10 x 16.5	24.0	10.7	10.7	16.0	11.5	0.4	17.5

• Packaging Specifications



Case size	W mm	Reel (pcs)	Carton (pcs)	Code
6.3 x 6.0	18	1,000	10,000	TR
6.3 x 7.7	18	1,000	10,000	
8 x 10	26	500	3,500	
8 x 12.5	26	500	3,500	
10 x 12.5	26	500	3,500	
10 x 12.8	26	500	3,500	

• Lead Free Type Reflow Soldering Condition

• Size Ø5~Ø10

- 1) Temperature at surface of capacitor shall not exceed T°C.
- 2) Period that temperature at the surface of capacitor becomes more than 200°C and T₁°C, shall not exceed t and t₁ seconds.
- 3) Preheat shall be made at 100°C~180°C and for maximum 120 seconds.
- 4) Please ensure that the capacitor became cold enough to the room temperature before the second reflow.

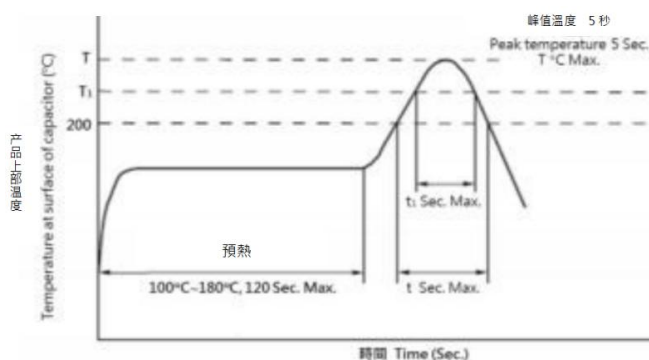
T%	t ₁ ≥ 230%	t ≥ 220%	≥ 200%	Reflow times
250	40	50	60	2
260	40	50	60	1

① T°C: Peak temperature

② Time more than 200°C

③ Time more than t₁

※ Please contact us if the condition is over the maximum.



• Recommended Land Size

unit: mm

Case size	X	Y	a
Ø 5	1.6	3.0	1.4
Ø 6.3	1.6	3.5	2.1
Ø 8	2.0	3.5	3.0
Ø 10	2.0	4.0	4.0

